

MARKET RESEARCH SUPPLY OF A HOT DIMPLING UNIT AND ASSOCIATED EQUIPMENT

Date: 22 - 10 - 2025

Protocol Number.: 5430 - 2025 - 10 - 939

A. SCOPE OF THE MARKET RESEARCH

The **Hellenic Aerospace Industry S.A.** (HAI S.A.) is conducting this Market Research in order to identify potential suppliers for the **Supply of a Hot Dimpling Unit and Accompanying Equipment** for its facilities located in **Tanagra**, **Viotia**, **Greece**.

The purpose of this Market Research is to collect technical and commercial information regarding the required equipment, as described below:

- 1. Main Unit (Control Unit)
- 2. Portable Ram Coin Dimpler
- 3. Accompanying Electrical & Pneumatic Equipment
- 4. Heating Elements & Spare Parts
- 5. Additional Accompanying Equipment & Consumables

The procurement will be conducted in accordance with the provisions set forth in ANNEX A and the detailed description contained therein.

B. Supporting Documents

The following Annexes form an integral part of this Market Research:

- Annex A: Technical Requirements and Specifications
- Annex B: Financial Offer Template

C. Financial Offer

- In their financial offer, participants must clearly state the proposed payment terms.
- **Desired payment term:** (to be completed by the prospective contractor)

Example Unit Disclaimer / Introduction

The Hot Dimpling Unit presented in Annex A (e.g., Zephyr ZT2409G) is provided solely as an illustrative example of the technical capabilities, performance, and features expected. It is intended to clarify the level of functionality required and to guide prospective contractors in understanding the desired technical characteristics.

Prospective contractors are encouraged to propose or submit offers for the example unit (e.g., Zephyr ZT2409G) or for similar units from other manufacturers, provided that the proposed units meet or exceed the technical requirements specified in Annex A. Reference to the example unit does not limit the choice of supplier or the model offered, nor should it be interpreted as a preference for the specific example.



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Suppliers are fully responsible for ensuring that their proposed equipment complies with all technical specifications in Annex A and is capable of safe, complete, and immediate operation, even if certain components, features, or accessories differ from the example unit.

D. SUBMISSION OF A BID

Following this Market Research and the attached Technical Specifications (Annex A), **Hellenic Aerospace Industry S.A.** (HAI S.A.) invites prospective contractors to submit their financial offer in accordance with **Annex B: Financial Offer Template**, exclusively to the following electronic address:

HAI.RFQ.56@haicorp.com

Deadline for submission: 31/10/2025, by 23:59 (local time), with the following reference clearly indicated in the email subject line: "SUPPLY OF A HOT DIMPLING UNIT AND ASSOCIATED EQUIPMENT 5430 – 2025-10-939 / RFQ56 / 31-10-2025"

For any questions or clarifications related to this Market Research, please contact us via email or telephone at the following details:

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Attachments:

- Annex A: Technical Requirements and Specifications
- Annex B: Financial Offer Template